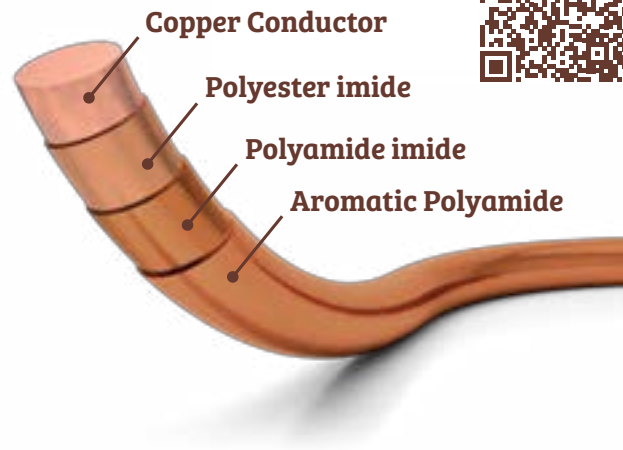


EmTherm 200 Bond

IEC 60317 - 38

EmTherm 200 Bond is a polyesterimide coated, self-bonding enamelled copper wire belonging in HC (200°C) thermal class, able to be manufactured in the diameter range of 0.20 - 0.80 mm.

EmTherm 200 Bond possess the feature of self-bonding through being kept at furnace at 160°-190°C temperature, blowing hot air at 200°C temperature, applying .



Fields of Use:

- Step motors
- Generators
- Air coils
- Speaker coils
- Brake coils

Thermal Class (°C)	Class HC, 200°C
Insulation Base Coat	THEIC Modified Polyesterimide
Insulation Top Coat	Polyamide imide
Insulation Bonding Layer	Aromatic Polyamide
Production Range (mm)	0.20 - 0.80 mm
Standards I.E.C	IEC 60317 - 38
Thermal Class (°C)	200°C
Heat Shock (°C)	≥ 220°C
Cut-Through Temperature (°C)	> 320°C
Soldering Temperature (°C)	Non-solderable
Bonding Temperature (°C)	160-190°C
Re-softening Temperature (°C)	190°C
Normal Solvent Resistance	5H
Dipping Varnish Resistance	Good
Refrigerant Resistance	Good
Transformer Oil Resistance	Non-usable
Distinct Features	Self-bonding via 120 A/mm ² current or ethyl/methyl alcohol application, keeping at furnace at 160-190°C temperature or blowing hot air at 200°C temperature; may be soldered with its Self-bonding upper layer; possess high mechanical strength.
Field of Use	Generators, electromechanics

● Copper conductor ● Self-bonding ⚡ 200°C thermal class

